

ON Semiconductor

FGB3040G2-F085 / FGD3040G2-F085 FGP3040G2-F085 / FGI3040G2-F085

EcoSPARK®2 300mJ, 400V, N-Channel Ignition IGBT

Features

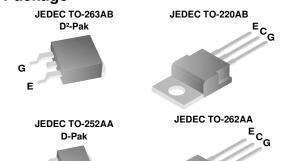
- SCIS Energy = 300mJ at T_J = 25°C
- Logic Level Gate Drive
- Qualified to AEC Q101
- RoHS Compliant



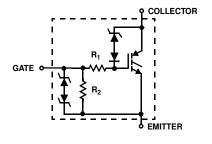
Applications

- Automotive Ignition Coil Driver Circuits
- Coil On Plug Applications

Package Symbol



COLLECTOR (FLANGE)





Symbol	Parameter	Ratings	Units
BV _{CER}	Collector to Emitter Breakdown Voltage (I _C = 1mA)	400	V
BV _{ECS}	Emitter to Collector Voltage - Reverse Battery Condition (I _C = 10mA)	28	V
E _{SCIS25}	Self Clamping Inductive Switching Energy (Note 1)	300	mJ
E _{SCIS150}	Self Clamping Inductive Switching Energy (Note 2)	170	mJ
I _{C25}	Collector Current Continuous, at V _{GE} = 5.0V, T _C = 25°C	41	Α
I _{C110}	Collector Current Continuous, at V _{GE} = 5.0V, T _C = 110°C	25.6	Α
V_{GEM}	Gate to Emitter Voltage Continuous	±10	V
D	Power Dissipation Total, at T _C = 25°C	150	W
P_D	Power Dissipation Derating, for T _C > 25°C	1	W/°C
TJ	Operating Junction Temperature Range	-55 to +175	°C
T _{STG}	Storage Junction Temperature Range	-55 to +175	°C
T _L	Max. Lead Temp. for Soldering (Leads at 1.6mm from case for 10s)	300	°C
T _{PKG}	Reflow soldering according to JESD020C	260	°C
ESD	HBM-Electrostatic Discharge Voltage at100pF, 1500Ω	4	kV
ESD	CDM-Electrostatic Discharge Voltage at 1Ω	2	kV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FGB3040G2	FGB3040G2-F085	TO-263AB	330mm	24mm	800
FGD3040G2	FGD3040G2-F085	TO-252AA	330mm	16mm	2500
FGP3040G2	FGP3040G2-F085	TO-220AB	Tube	N/A	50
FGI3040G2	FGI3040G2-F085	TO-262AA	Tube	N/A	50

Electrical Characteristics T_A = 25°C unless otherwise noted

Symbol Parameter Test Conditions Min Typ Max Ur

Off State Characteristics

BV _{CER}	Collector to Emitter Breakdown Voltage	$I_{CE} = 2mA, V_{GE} = 0,$ $R_{GE} = 1K\Omega,$ $T_{J} = -40 \text{ to } 150^{\circ}\text{C}$		370	400	430	٧
BV _{CES}	Collector to Emitter Breakdown Voltage	$T_{\rm J} = -40 \text{ to } 150^{\rm o}\text{C}$		390	420	450	٧
BV _{ECS}	Emitter to Collector Breakdown Voltage	$I_{CE} = -20 \text{mA}, V_{GE} = 0 \text{V},$ $T_{J} = 25 ^{\circ} \text{C}$		28	-	1	V
BV _{GES}	Gate to Emitter Breakdown Voltage	I _{GES} = ±2mA		±12	±14	-	V
	Collector to Emitter Leakage Current	V_{CE} = 250V, R_{GE} = 1K Ω	$T_J = 25^{\circ}C$	-	-	25	μΑ
ICER	Collector to Emitter Leakage Current		$T_{J} = 150^{\circ}C$	-	-	1	mA
	Emitter to Collector Leakage Current	V _{EC} = 24V,	$T_{J} = 25^{\circ}C$	-	-	1	mA
I _{ECS}	Emitter to Collector Leakage Current		$T_{J} = 150^{\circ}C$	-	-	40	IIIA
R ₁	Series Gate Resistance			-	120	-	Ω
R ₂	Gate to Emitter Resistance			10K	-	30K	Ω

On State Characteristics

	Collector to Emitter Saturation Voltage		$T_{J} = 25^{\circ}C$	-	1.15	1.25	٧
V _{CE(SAT)}	Collector to Emitter Saturation Voltage	I_{CE} = 10A, V_{GE} = 4.5V,	$T_J = 150^{\circ}C$	-	1.35	1.50	V
V _{CE(SAT)}	Collector to Emitter Saturation Voltage	$I_{CE} = 15A, V_{GE} = 4.5V,$	$T_J = 150^{\circ}C$	-	1.68	1.85	V
E _{SCIS}	Self Clamped Inductive Switching	L = 3.0 mHy,RG = 1K Ω , VGE = 5V, (Note 1)	TJ = 25°C	1	-	300	mJ
		VGE = 5V, (NOIE I)					

Thermal Characteristics

R ₀ JC Thermal Resistance Junction to Case	-	-	1	°C/W
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Notes:

1: Self Clamping Inductive Switching Energy (E_{SCIS25}) of 300 mJ is based on the test conditions that starting Tj=25°C; L=3mHy, I_{SCIS} =14.2A, V_{CC} =100V during inductor charging and V_{CC} =0V during the time in clamp.

2: Self Clamping Inductive Switching Energy ($E_{SCIS150}$) of 170 mJ is based on the test conditions that starting Tj=150°C; L=3mHy, I_{SCIS} =10.8A, V_{CC} =100V during inductor charging and V_{CC} =0V during the time in clamp.

Max Units

Min

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Parameter

Dynamic Characteristics							
Q _{G(ON)}	Gate Charge	I _{CE} = 10A, V _{CE} = 12V, V _{GE} = 5V			21	-	nC
V	Gate to Emitter Threshold Voltage	I _{CE} = 1mA, V _{CE} = V _{GE,}	$T_{\rm J} = 25^{\rm o}{\rm C}$	1.3	1.7	2.2	V
V _{GE(TH)}	Cate to Emitter Threshold Voltage		$T_{\rm J} = 150^{\rm o}{\rm C}$	0.75	1.2	1.8	v
V_{GEP}	Gate to Emitter Plateau Voltage	V _{CE} = 12V, I _{CE} = 10A		-	2.8	-	V

Test Conditions

Switching Characteristics

Symbol

$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	02 . 2	-	0.9	4	μS
t_{rR}	Current Rise Time-Resistive	$V_{GE} = 5V, R_{G} = 1K\Omega$ $T_{J} = 25^{\circ}C,$	-	1.9	7	μS
t _{d(OFF)L}	Current Turn-Off Delay Time-Inductive	OL ,	-	4.8	15	μS
t _{fL}	Current Fall Time-Inductive	$V_{GE} = 5V, R_{G} = 1K\Omega$ $I_{CE} = 6.5A, T_{J} = 25^{\circ}C,$	-	2.0	15	μS

Typical Performance Curves

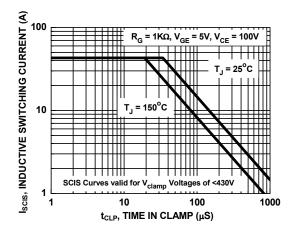


Figure 1. Self Clamped Inductive Switching Current vs. Time in Clamp

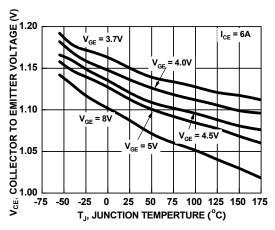


Figure 3. Collector to Emitter On-State Voltage vs. Junction Temperature

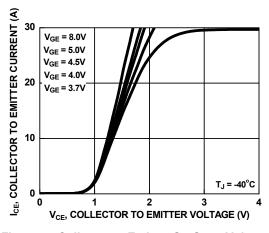


Figure 5. Collector to Emitter On-State Voltage vs. Collector Current

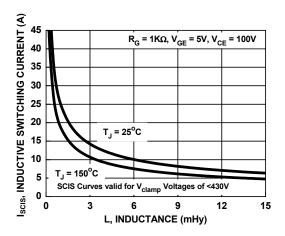


Figure 2. Self Clamped Inductive Switching Current vs. Inductance

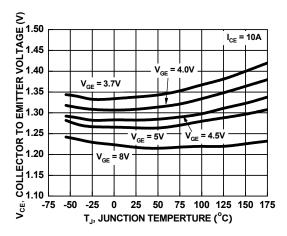


Figure 4. Collector to Emitter On-State Voltage vs. Junction Temperature

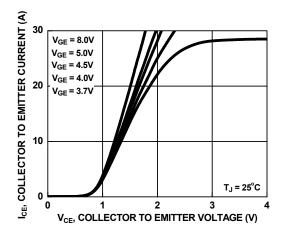


Figure 6. Collector to Emitter On-State Voltage vs. Collector Current

Typical Performance Curves (Continued)

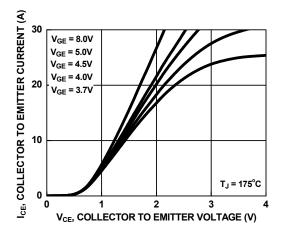


Figure 7. Collector to Emitter On-State Voltage vs. Collector Current

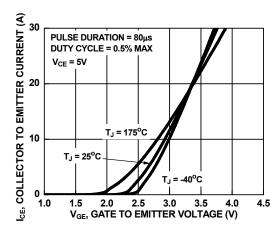


Figure 8. Transfer Characteristics

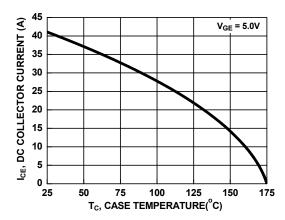


Figure 9. DC Collector Current vs. Case Temperature

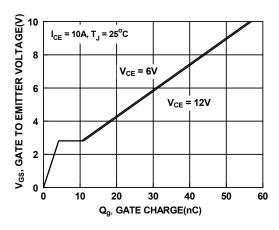


Figure 10. Gate Charge

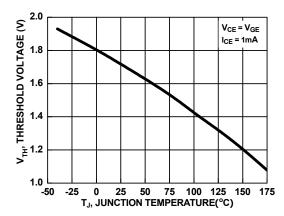


Figure 11. Threshold Voltage vs. Junction Temperature

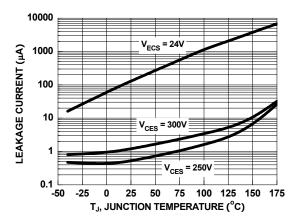
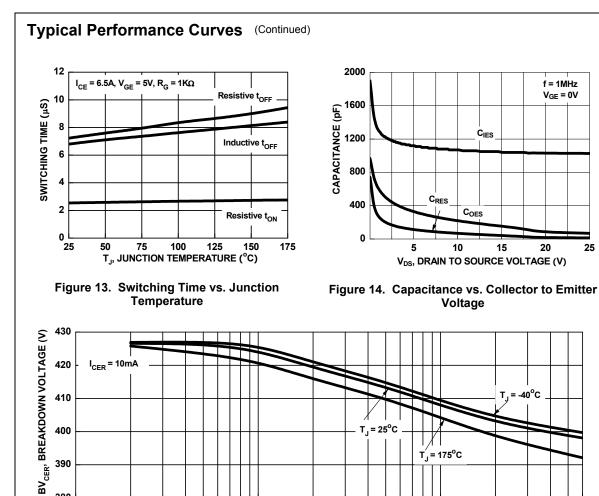


Figure 12. Leakage Current vs. Junction Temperature

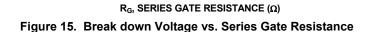
25

6000



390

380 10



 $T_{J}^{'} = 175^{\circ}C$

1000

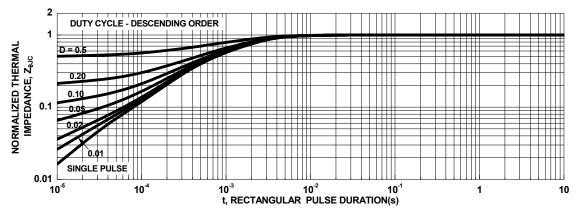


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

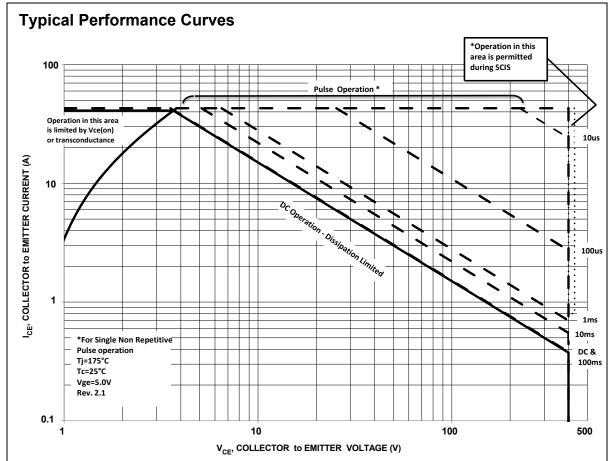


Figure 17. Forward Safe Operating Area

Test Circuit and Waveforms

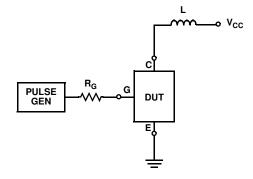


Figure 18. Inductive Switching Test Circuit

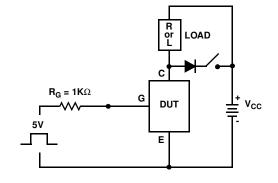


Figure 19. t_{ON} and t_{OFF} Switching Test Circuit

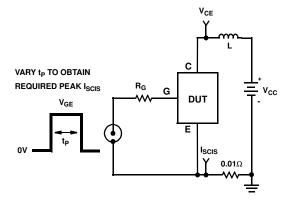


Figure 20. Energy Test Circuit

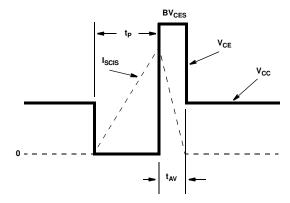


Figure 21. Energy Waveforms

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